



Material Content Data Sheet



Sales Product Name		BAS 28W H6327		Issued		27. September 2017		
MA#		MA000842972						
Package		PG-SOT343-4-3		Weight*		6.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.004	0.06		598	
	non noble metal	arsenic	7440-38-2	0.000	0.00		6	
	inorganic material	silicon	7440-21-3	0.035	0.51	0.57	5107	5711
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		96	
	non noble metal	titanium	7440-32-6	0.003	0.05		481	
	non noble metal	chromium	7440-47-3	0.010	0.14		1444	
	non noble metal	copper	7440-50-8	3.239	47.94	48.14	479384	481405
wire	non noble metal	copper	7440-50-8	0.004	0.06	0.06	630	630
encapsulation	organic material	carbon black	1333-86-4	0.031	0.45		4534	
	plastics	epoxy resin	-	0.659	9.75		97483	
	inorganic material	silicondioxide	60676-86-0	2.375	35.14	45.34	351393	453410
leadfinish	non noble metal	tin	7440-31-5	0.199	2.95	2.95	29483	29483
plating	noble metal	silver	7440-22-4	0.198	2.94	2.94	29361	29361
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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